



Low Power 5V 250kbps/1Mbps/20Mbps 256-Fanout RS485 Transceivers with True Fail Safe



Features

- Meets or exceeds the requirements of ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E) specifications for V_{CC} at $+5V \pm 10\%$
- Low quiescent current: 0.4mA typ., 0.9mA max.
- Low shutdown current (where applicable): 1nA typical, 10 μ A max.
- Guaranteed standard data rate 250kbps, 1Mbps, or 20Mbps
- True Fail-Safe (Open, Short, Bus Idle) Receiver
- -7V to +12V common-mode input voltage range
- Half-Duplex or Full-Duplex mode configuration
- Allows up to 1/8 unit load (256 devices) on the same common bus
- Controlled driver output slew rate and receiver input filtering
- Active-high driver enable and active-low receiver enable
- ESD protection on bus terminals $\pm 15kV$ Human Body Model (HBM)
- Alternative replacement for MAX308xE series, SN75HVD3082E, and SN65HVD3082E series.

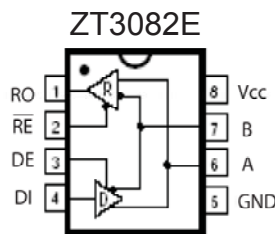
General Description

The ZT308xE series devices are 5V differential data line transceivers for RS485/RS422 communication that consist of one driver and one receiver with high level of ESD protection. They are designed for balanced transmission lines interface that meet ANSI standard TIA/EIA-485-A and ISO 8482:1987(E) specifications.

The ZT308xE series devices spans out with half or full duplex, data rate guaranteed at 250kbps, 1Mbps, or 20Mbps and allow one-eighth of an unit load that fan out 256 devices sharing a common bus. The I/Os are enhanced-electrostatic discharge (ESD) protected, exceeding $\pm 15kV$ Human Body Model (HBM).

Applications

- RS422/RS485 communications
- Utility meters
- Industrial process control
- Building automation
- Level translators
- Transceivers for EMI-sensitive applications
- Routers and HUBs
- Industrial-controlled Local Area Networks
- Industrial PCs, embedded PCs and peripherals
- Industrial, security CATV and camera applications



Product Selection Guide And Cross Reference

Part Number	Duplex	# Of Tx/ Rx	Data Rate (Mbps)	# of Tx/ Rx on Bus	Slew Rate Limit	Low-Power Shutdown	Tx/ Rx Enable	ESD on Tx/ Rx	Package Types	Pin-to-Pin Cross Reference	Industry Standard Pinout
ZT3080E ZT3080J	Full	1/1	.250	256	Yes	Yes	Yes	$\pm 15kV$	14-PDIP, 14-nSOIC	MAX3080E SN65HVD3080E	75180
ZT3081E	Full	1/1	.250	256	Yes	No	No	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3081E SN65HVD3081E	75179
ZT3082E	Half	1/1	.250	256	Yes	Yes	Yes	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3082E SN65HVD3082E	75176
ZT3083E ZT3083J	Full	1/1	1	256	Yes	Yes	Yes	$\pm 15kV$	14-PDIP, 14-nSOIC	MAX3083E, SN65HVD3083E	75180
ZT3084E	Full	1/1	1	256	Yes	No	No	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3084E SN65HVD3084E	75179
ZT3085E	Half	1/1	1	256	Yes	Yes	Yes	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3085E, SN65HVD3085E	75176
ZT3086E ZT3086J	Full	1/1	20	256	No	Yes	Yes	$\pm 15kV$	14-PDIP, 14-nSOIC	MAX3086E SN65HVD3086E	75180
ZT3087E	Full	1/1	20	256	No	No	No	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3087E SN65HVD3087E	75179
ZT3088E	Half	1/1	20	256	No	Yes	Yes	$\pm 15kV$	8-PDIP, 8-nSOIC, 8-MSOP	MAX3088E SN65HVD3088E	75176



Absolute Maximum Ratings

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Power Supply, (V_{CC}).....-0.3V to +7.0V

Input Voltages

DI, DE, \overline{RE} -0.3V to ($V_{CC} + 0.3V$)

Differential Input Voltage, (V_{ID}) -12V to +12V

A, B (V_I) -9V to +13V

Output Voltages

RO -0.3V to +6.0V

Y, Z (A & B on Half Duplex) -9V to +13.0V

Operating Temperature.....-40°C to +85°C

Storage Temperature.....-65°C to +150°C

Power Dissipation Per Package

8-pin PDIP (derate 9.09mW/°C above +70°C) 722mW

8-pin nSOIC (derate 6.14mW/°C above +70°C)..... 500mW

8-pin MSOP (derate 4.85mW/°C above +70°C)..... 400mW

14-pin PDIP (derate 10.00mW/°C above +70°C) 800mW

14-pin nSOIC (derate 8.33mW/°C above +70°C).... 667mW

Storage Considerations

Storage in a low humidity environment is preferred. Large high density plastic packages are moisture sensitive and should be stored in Dry Vapor Barrier Bags. Prior to usage, the parts should remain bagged and stored below 40°C and 60%RH. If the parts are removed from the bag, they should be used within 168 hours or stored in an environment at or below 20%RH. If the above conditions cannot be followed, the parts should be baked for 12 hours at 125°C in order to remove moisture prior to soldering. Zywyn ships product in Dry Vapor Barrier Bags with a humidity indicator card and desiccant pack. The humidity indicator should be below 30%RH. The MSL of this product is 3.

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DC Electrical Characteristics

Unless otherwise stated, $V_{CC} = +5.0V \pm 10\%$, $T_A = T_{min}$ to T_{max} , typical values apply at $V_{CC} = +5.0V$ and $T_A = 25^\circ C$.

Parameter	Condition	Min	Typ	Max	Units
Operating Voltage & Temperature					
Temperature	Industrial Grade	-40	25	85	°C
V_{CC} Voltage Range	$V_{CC} = +5.0V$	4.50	5	5.5	V
Supply Current					
I_{CC} , Tx and Rx active	DI= V_{CC} /GND, DE= V_{CC} , \overline{RE} =GND, RS485 I/O=Open		400	900	μA
I_{CC} , Tx active	DI= V_{CC} /GND, DE= V_{CC} , \overline{RE} = V_{CC} , RS485 I/O=Open		400	900	μA
I_{CC} , Rx active	DI= V_{CC} /GND, DE=GND, \overline{RE} =GND, RS485 I/O=Open		400	900	μA
I_{SD} , Shutdown Current (except ZT3081E, ZT3084E, and ZT3087E)	DI= V_{CC} /GND, DE = GND, $\overline{RE} = V_{CC}$, RS485 I/O=Open		0.001	10	μA
TTL LOGIC Input, Driver					
Input Threshold Low, V_{IL}	$V_{CC} = +5.0V$, DE, DI, and \overline{RE}			0.8	V
Input Threshold High, V_{IH}	$V_{CC} = +5.0V$, DE, DI, and \overline{RE}	2			V
TTL LOGIC Output, Receiver					
Output Voltage Low, V_{OL}	$I_{OUT} = +4mA$			0.4	V
Output Voltage High, V_{OH}	$I_{OUT} = -4mA$	$V_{CC}-1.5$			V
Output Leakage Current	Receiver Outputs Disabled, $V_{OUT} = 0.4V$ to $2.4V$			± 1	μA
Short Circuit Current	$V_{OUT} = 0V$ to V_{CC}			± 95	mA
Receiver Input					
Input Current	DE = 0V, $V_{CC} = 0V$ to $5.5V$, $V_{IN} = +12V$			125	μA
	DE = 0V, $V_{CC} = 0V$ to $5.5V$, $V_{IN} = -7V$			-75	μA
Differential Threshold Voltage, V_{TH}	$V_{CM} = 0V$, $V_{CC} = +5.0V$, $T_A = 25^\circ C$	-0.2		0.2	V
Input Hysteresis			25		mV
Input Resistance, R_{IN}	$V_{CM} = -7V$ to $+12V$	96			k Ω
Transmitter Output					
Differential Output Voltage, V_{OD1}	No Load			5	V
Differential Output Voltage, V_{OD2}	With $R_L = 50\Omega$, Refer to Figure 1. (RS422)	2			V
	With $R_L = 27\Omega$, Refer to Figure 1. (RS485)	1.5		5	V
Driver Common Mode Output, V_{OC}	With $R_L = 27\Omega$ or 50Ω . $C_L = 50pF$. Refer to Figure 3.			3	V
Change in Voltage Magnitude for Differential States, ΔV_{OD}	Differential Output Voltage, with $R_L = 27\Omega$ or 50Ω , Refer to Figure 1			0.2	V
Change in Voltage Magnitude for Common Mode States, ΔV_{OC}	Common-Mode Output Voltage, with $R_L = 27\Omega$ or 50Ω . Refer to Figure 2.			0.2	V
Transmitter Short-Circuit Current	$V_{OUT} = -7V$ to $+12V$. Refer to Figure 7.	-250		250	mA

AC Electrical Characteristics (ZT3080E - ZT3082E)

Unless otherwise stated, $V_{CC} = +5.0V$, $T_A = T_{min}$ to T_{max} , typical values apply at $V_{CC} = +5.0V$ and $T_A = 25^\circ C$.

Parameter	Condition	Min	Typ	Max	Units
Transmitter Timing					
Transmitter Propagation t_{PLH}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		700	1300	ns
Transmitter Propagation t_{PHL}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		700	1300	ns
Transmitter Output Skew t_{SK}	$ t_{PLH} - t_{PHL} $		20	200	ns
Transmitter Rise/Fall Time	t_r, t_f , $R_{DIFF} = 54\Omega$, $C_L = 50pF$, Refer to Figure 4.	500	900	1500	ns
Transmitter Output Enable	To Output HIGH, t_{PZH} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		2500	7000	ns
	To Output LOW, t_{PZL} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		2500	7000	ns
Transmitter Output Disable	From Output HIGH, t_{PHZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		80	200	ns
	From Output LOW, t_{PLZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		80	200	ns
Receiver Timing					
Receiver Propagation t_{PLH}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.		75	200	ns
Receiver Propagation t_{PHL}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.		79	200	ns
Differential Receiver Skew t_{SK}	$ t_{PLH} - t_{PHL} $		4	± 30	ns
Receiver Output Enable	To Output HIGH, t_{PZH} , $C_L = 15pF$. Refer to Figure 10.		5	50	ns
	To Output LOW, t_{PZL} , $C_L = 15pF$. Refer to Figure 11.		10	50	ns
Receiver Output Disable	From Output HIGH, t_{PHZ} , $C_L = 15pF$. Refer to Figure 10.		5	50	ns
	From Output LOW, t_{PLZ} , $C_L = 15pF$. Refer to Figure 11.		8	50	ns
Shutdown Timing					
Time to Shutdown, t_{SHDN}			200	600	ns
Transmitter Enable from SHUTDOWN to Output HIGH	$C_L = 50pF$, $t_{PZH(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 5.		3500	7000	ns
Transmitter Enable from SHUTDOWN to Output LOW	$C_L = 50pF$, $t_{PZL(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 6.		3500	7000	ns
Receiver Enable from SHUTDOWN to Output HIGH	$C_L = 15pF$, $t_{PZH(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 10.		1600	3500	ns
Receiver Enable from SHUTDOWN to Output LOW	$C_L = 15pF$, $t_{PZL(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 11.		1600	3500	ns
Transceiver Throughput					
Maximum Data Rate		250			kbps
ESD Tolerance					
ESD HBM	RS485 Inputs and Outputs		± 15		kV
ESD HBM ⁽¹⁾	All Pins		± 4		kV

(1) Tested in accordance with JEDEC Standard 22, Test Method A114-A and IEC 60749-26

AC Electrical Characteristics (ZT3083E - ZT3085E)

Unless otherwise stated, $V_{CC} = +5.0V$, $T_A = T_{min}$ to T_{max} , typical values apply at $V_{CC} = +5.0V$ and $T_A = 25^\circ C$.

Parameter	Condition	Min	Typ	Max	Units
Transmitter Timing					
Transmitter Propagation t_{PLH}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		150	500	ns
Transmitter Propagation t_{PHL}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		150	500	ns
Transmitter Output Skew t_{SK}	$ t_{PLH} - t_{PHL} $		5	50	ns
Transmitter Rise/Fall Time	t_r , t_f , $R_{DIFF} = 54\Omega$, $C_L = 50pF$, Refer to Figure 4.		350	550	ns
Transmitter Output Enable	To Output HIGH, t_{PZH} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		1000	2500	ns
	To Output LOW, t_{PZL} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		1000	2500	ns
Transmitter Output Disable	From Output HIGH, t_{PHZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		60	100	ns
	From Output LOW, t_{PLZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		60	100	ns
Receiver Timing					
Receiver Propagation t_{PLH}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.		75	200	ns
Receiver Propagation t_{PHL}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.		75	200	ns
Differential Receiver Skew t_{SK}	$ t_{PLH} - t_{PHL} $		4	± 30	ns
Receiver Output Enable	To Output HIGH, t_{PZH} , $C_L = 15pF$. Refer to Figure 10.		5	50	ns
	To Output LOW, t_{PZL} , $C_L = 15pF$. Refer to Figure 11.		10	50	ns
Receiver Output Disable	From Output HIGH, t_{PHZ} , $C_L = 15pF$. Refer to Figure 10.		5	50	ns
	From Output LOW, t_{PLZ} , $C_L = 15pF$. Refer to Figure 11.		8	50	ns
Shutdown Timing					
Time to Shutdown, t_{SHDN}			200	600	ns
Transmitter Enable from SHUTDOWN to Output HIGH	$C_L = 50pF$, $t_{PZH(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 5.		2500	4500	ns
Transmitter Enable from SHUTDOWN to Output LOW	$C_L = 50pF$, $t_{PZL(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 6.		2500	4500	ns
Receiver Enable from SHUTDOWN to Output HIGH	$C_L = 15pF$, $t_{PZH(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 10.		1600	3500	ns
Receiver Enable from SHUTDOWN to Output LOW	$C_L = 15pF$, $t_{PZL(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 11.		1700	3500	ns
Transceiver Throughput					
Maximum Data Rate		1			Mbps
ESD Tolerance					
ESD HBM	RS485 Inputs and Outputs		± 15		kV
ESD HBM ⁽¹⁾	All Pins		± 4		kV

(1) Tested in accordance with JEDEC Standard 22, Test Method A114-A and IEC 60749-26

AC Electrical Characteristics (ZT3086E - ZT3088E)

Unless otherwise stated, $V_{CC} = +5.0V$, $T_A = T_{min}$ to T_{max} , typical values apply at $V_{CC} = +5.0V$ and $T_A = 25^\circ C$.

Parameter	Condition	Min	Typ	Max	Units
Transmitter Timing					
Transmitter Propagation t_{PLH}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		12	20	ns
Transmitter Propagation t_{PHL}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$. Refer to Figure 4.		12	20	ns
Transmitter Output Skew t_{SK}	$ t_{PLH} - t_{PHL} $		1.4	2	ns
Transmitter Rise/Fall Time	$t_r, t_f, R_{DIFF} = 54\Omega$, $C_L = 50pF$, Refer to Figure 4.		7	15	ns
Transmitter Output Enable	To Output HIGH, t_{PZH} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		13	30	ns
	To Output LOW, t_{PZL} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		13	30	ns
Transmitter Output Disable	From Output HIGH, t_{PHZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 5.		12	30	ns
	From Output LOW, t_{PLZ} , $C_L = 50pF$, $R_L = 110\Omega$. Refer to Figure 6.		12	30	ns
Receiver Timing					
Receiver Propagation t_{PLH}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.			100	ns
Receiver Propagation t_{PHL}	$C_L = 15pF$, $ V_{ID} \geq 2.0V$; rise and fall time of $V_{ID} \leq 15ns$ Refer to Figure 9.			100	ns
Differential Receiver Skew t_{SK}	$ t_{PLH} - t_{PHL} $			10	ns
Receiver Output Enable	To Output HIGH, t_{PZH} , $C_L = 15pF$. Refer to Figure 10.			30	ns
	To Output LOW, t_{PZL} , $C_L = 15pF$. Refer to Figure 11.			30	ns
Receiver Output Disable	From Output HIGH, t_{PHZ} , $C_L = 15pF$. Refer to Figure 10.			30	ns
	From Output LOW, t_{PLZ} , $C_L = 15pF$. Refer to Figure 11.			30	ns
Shutdown Timing					
Time to Shutdown, t_{SHDN}			200	600	ns
Transmitter Enable from SHUTDOWN to Output HIGH	$C_L = 50pF$, $t_{PZH(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 5.		1600	2600	ns
Transmitter Enable from SHUTDOWN to Output LOW	$C_L = 50pF$, $t_{PZL(SHDN)}$, $R_L = 110\Omega$. Refer to Figure 6.		1600	2600	ns
Receiver Enable from SHUTDOWN to Output HIGH	$C_L = 15pF$, $t_{PZH(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 10.		1600	3500	ns
Receiver Enable from SHUTDOWN to Output LOW	$C_L = 15pF$, $t_{PZL(SHDN)}$, $R_L = 1k\Omega$. Refer to Figure 11.		1700	3500	ns
Transceiver Throughput					
Maximum Data Rate		20			Mbps
ESD Tolerance					
ESD HBM	RS485 Inputs and Outputs		± 15		kV
ESD HBM ⁽¹⁾	All Pins		± 4		kV

(1) Tested in accordance with JEDEC Standard 22, Test Method A114-A and IEC 60749-26

Pin Description

Pin Numbers				Name	Description
Half Duplex	Full Duplex				
ZT3082E	ZT3081E	ZT3080E	ZT3080J		
ZT3085E	ZT3084E	ZT3083E	ZT3083J		
ZT3088E	ZT3087E	ZT3086E	ZT3086J		
1	2	2	2	RO	Receiver Output. If A>B by 200mV, then RO = HIGH; if A<B by 200mV, then RO = LOW
2	n/a	3	3	\overline{RE}	Receiver Output Enable Low active input RO is high-Z when \overline{RE} = HIGH
3	n/a	4	4	DE	Driver Output Enable. The transmitter outputs, Y and Z, are enabled when DE = HIGH. The outputs are high-Z when DE = LOW
4	3	5	5	DI	Driver Input. A low on DI forces output Y low and output Z high. A high on DI will bring output Y high and output Z low
5	4	6, 7	6, 7	GND	Analog Ground
n/a	5	9	9	Y	Non-inverting transmitter output
n/a	6	10	10	Z	Inverting transmitter output
6	n/a	n/a	n/a	A	Non-inverting transmitter output and non-inverting receiver input.
n/a	8	12	12	A	Non-inverting receiver input.
7	n/a	n/a	n/a	B	Inverting transmitter output and inverting receiver input.
n/a	7	11	11	B	Inverting receiver input
8	1	14	13, 14	VCC	Power Supply Input, 5V \pm 10%
n/a	n/a	1, 8, 13	1, 8	NC	No Connect, Not internally connected.

Circuit Description

The ZT308xE series are low-power transceivers for RS-485 and RS-422 communications. The RS-485 standard is ideal for multi-drop applications and for long-distance interfaces. The TIA/EIA-485 specification allows up to 256 drivers and 256 receivers to be connected to a data bus, making it an ideal choice for multi-drop applications. RS-485 transceivers are equipped with a wide (-7V to +12V) common mode range to accommodate ground potential differences since the cabling can be as long as 4,000 feet. As RS-485 is a differential interface, data is virtually immune to noise in the transmission line.

RS-485 Transmitters

Each device in the ZT308xE family contains a differential output line transmitter that can drive voltage into multiple loads on a terminated two-wire pair, and a receiver that accepts a differential voltage down to 200mV. The transmitter's differential output can comply with RS-485 and also RS-422 standards. The typical voltage output swing with no load is 0V to V_{CC} . With worst case loading of 54 ohms across the differential outputs, the drivers can maintain greater than 1.5V voltage levels, which is more than adequate for a differential receiver to acknowledge a logic state. The 54 ohms is the equivalent of two 120 ohm termination resistors placed on each side of the transmission line and the input impedance of 256 receivers on the line. The ZT3082E, ZT3085E, and ZT3088E transmitter have an enable control line which is active HIGH. A logic HIGH on DE (pin 3) will enable the differential outputs. A logic LOW on DE (pin 3) will disable the transmitter outputs. While disabled, the transmitter outputs are in high impedance.

RS-485 Receivers

Each transceiver contains one differential receiver that has an input sensitivity of 200mV. The input impedance of the receivers is typically 96 kohms. A wide common mode range of -7V to +12V allows for large ground potential differences between systems.

The ZT3082E, ZT3085E, and ZT3088E receivers have an enable control input. A logic LOW on \overline{RE} will enable the receiver, a logic HIGH on \overline{RE} will disable the receiver. The receivers are equipped with the true fail-safe feature, which guarantees that the receiver output to be in a HIGH-IMPEDANCE state when the input is left unconnected. When the receiver inputs are either open or short circuit, the receiver output will be in a HIGH state when \overline{RE} enable is LOW.

The ZT3080E, ZT3081E, and ZT3082E can transmit and receive at data rates up to 250kbps. The ZT3083E, ZT3084E, and ZT3085E can transmit and receive at data rates up to 1Mbps. The ZT3086E, ZT3087E, and ZT3088E can transmit and receive at data rates up to 20Mbps.

Bus Configuration

The ZT3080E, ZT3081E, ZT3083E, ZT3084E, ZT3086E, and ZT3087E are full-duplex transceivers, while the ZT3082E, ZT3085E, and ZT3088E are half-duplex.

For full duplex, the devices are used as a four-wire bus transceiver with a configuration that the transmitters and receivers are moving data independent of each other. Transmit can occur on a dedicated two-wire pair and receive can occur on an adjacent two-wire pair, with each pair transferring data.

Half duplex is a configuration where the transmitter outputs are connected to its receiver inputs. This application is common for two-wire interfaces where either the transmitter is active or the receiver is active. It is common to connect the enable inputs for the transmitter and receiver together so that a logic HIGH will enable the transmitter and disable the receiver. Conversely, a logic LOW will disable the transmitter and enable the receiver. Half-duplex configurations and these devices are designed for bidirectional data transmission on multipoint twisted-pair cables for applications, such as digital motor controllers, remote sensors and terminals, industrial process control, security stations and environmental control systems.

ESD Immunity

Electro-Static Discharge (ESD) is an important factor when implementing a serial port into a system, especially in harsh environmental conditions. These industrial strength devices provide extra protection against ESD and are intended for harsh environments where high-speed data communication is important.

All of the devices in the ZT308xE series of transceivers incorporate internal protection structures on all pins to protect against ESD charges encountered during handling and assembly. The driver outputs and receiver inputs have extra protection against static electricity as they are directly interfacing to the outside environment. As such, these pins against ESD of $\pm 15kV$ without damage in all states of the transceiver's operation in the static state. After multiple ESD events, Zywyn's ZT308xE family of transceivers keep working without latchup. These devices eliminate the need for external transient suppressor diodes and the associated high capacitance loading, allowing reliable high-speed data communications.

The Human Body Model has been the generally accepted ESD testing method for semiconductors. This test is intended to simulate the human body's potential to store electrostatic energy and discharge it to an integrated circuit upon close proximity or contact. This method will test the IC's capability to withstand an ESD transient during normal handling such as in manufacturing areas where the ICs tend to be handled frequently.

Function Table

ZT3082E, ZT3085E, and ZT3088E

DRIVER				RECEIVER		
Input DI	Enable DE	Outputs		Differential Inputs $V_{ID} = V_A - V_B$	Enable \overline{RE}	Output RO
		A	B			
H	H	H	L	$V_{ID} \leq -0.2V$	L	L
L	H	L	H	$-0.2V < V_{ID} < +0.2V$	L	U
X	L	Z	Z	$+0.2V \leq V_{ID}$	L	H
Open	H	H	L	X	H	Z
X	Open	Z	Z	Open circuit	L	H*
				Short circuit	L	H*
				X	Open	Z

ZT3081E, ZT3084E, and ZT3087E

DRIVER			RECEIVER	
Input DI	Outputs		Differential Inputs $V_{ID} = V_A - V_B$	Output RO
	Y	Z		
H	H	L	$V_{ID} \leq -0.2V$	L
L	L	H	$-0.2V < V_{ID} < +0.2V$	U
X	Z	Z	$+0.2V \leq V_{ID}$	H
Open	H	L	X	Z
X	Z	Z	X	Z

ZT3080E, ZT3080J, ZT3083E, ZT3083J, ZT3086E, and ZT3086J

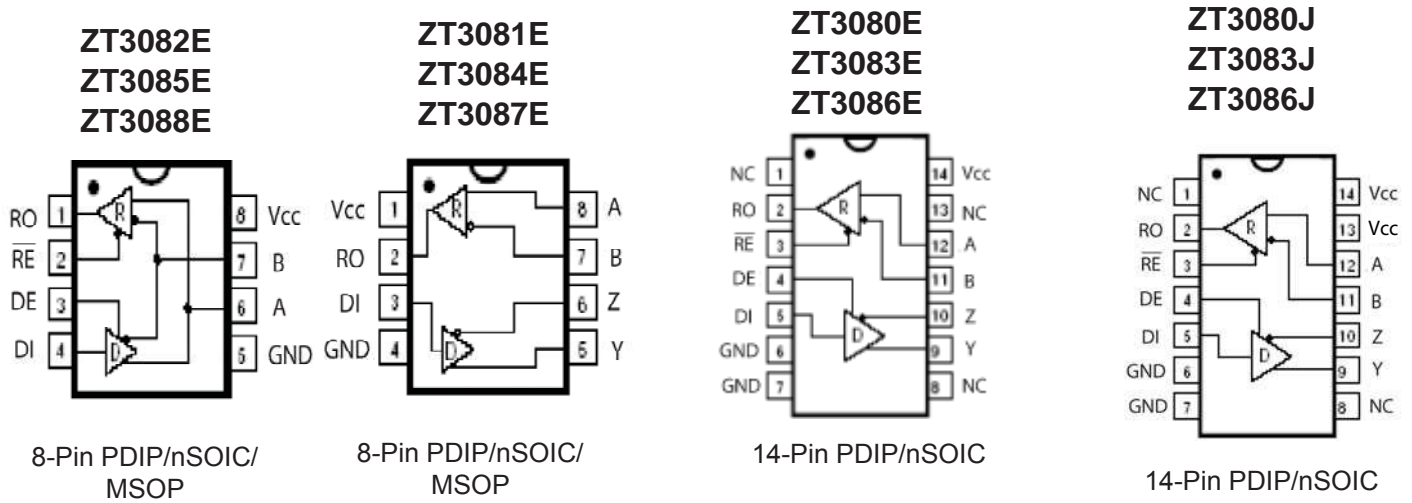
DRIVER				RECEIVER		
Input DI	Enable DE	Outputs		Differential Inputs $V_{ID} = V_A - V_B$	Enable \overline{RE}	Output RO
		Y	Z			
H	H	H	L	$V_{ID} \leq -0.2V$	L	L
L	H	L	H	$-0.2V < V_{ID} < +0.2V$	L	U
X	L	Z	Z	$+0.2V \leq V_{ID}$	L	H
Open	H	H	L	X	H	Z
X	Open	Z	Z	X	Open	Z

Note:

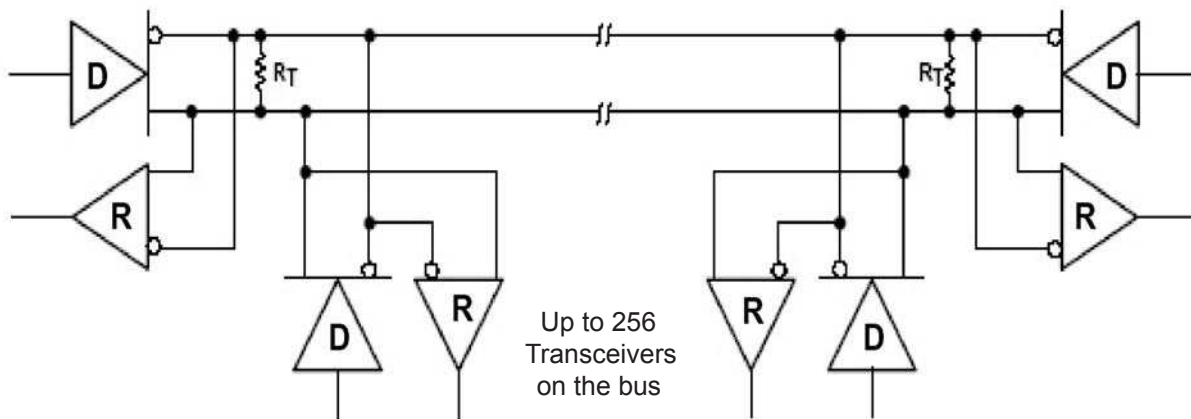
H = High Level; L = Low Level; Z = High Impedance; X = Irrelevant; U = Undetermined State.

* = Fail Safe (Receiver Output High) when Receiver Inputs are Open or Short and Common Mode equals to 0V.

Pin Configuration



Typical Application Circuits



Notes:

- A. The bus should be terminated at both ends in its characteristic impedance of $R_T = Z_0$.
- B. Stub lengths off the main bus should be kept as short as possible.
- C. Can connect up to 256 devices on the same common bus.

Typical Test Circuits

Notes:

- A. The test load capacitance includes probe and test jig capacitance, unless otherwise specified.
- B. The signal generator had the following characteristics:
Pulse rate = 1000 kHz, 50% duty cycle, $Z_O = 50\Omega$, t_r & $t_f < 6ns$, unless otherwise specified.

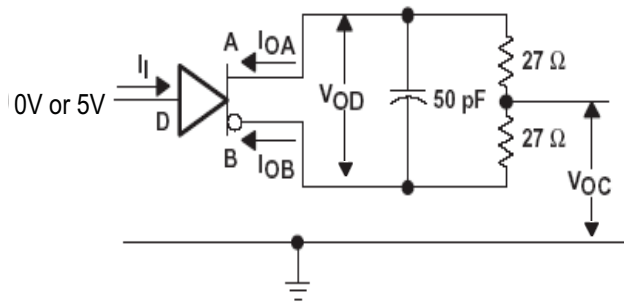


Figure 1. Driver Test Circuit, V_{OD} and V_{OC} Without Common-Mode Loading

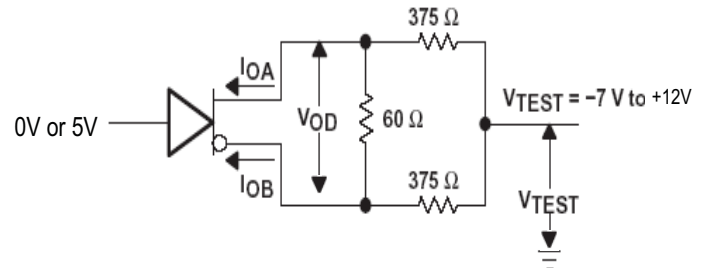


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading

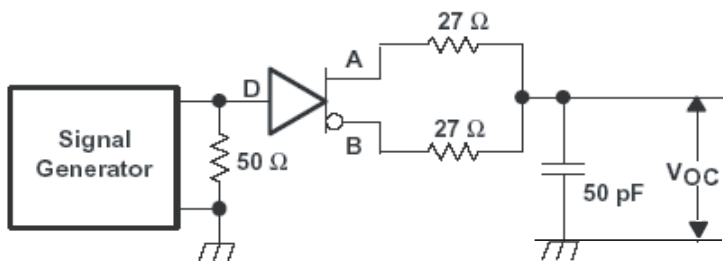


Figure 3. Driver Common-Mode Output Voltage (V_{OC}) Test Circuit and Waveforms

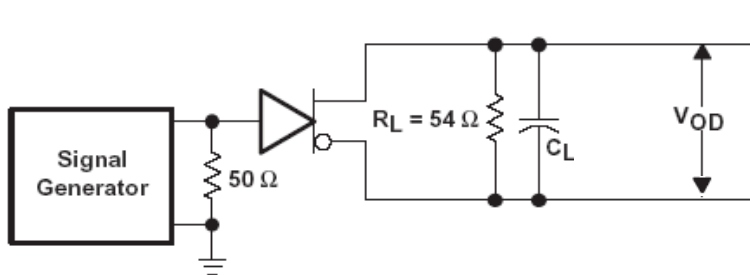


Figure 4. Driver Differential Output Voltage (V_{OD}) Switching Test Circuit and Waveforms

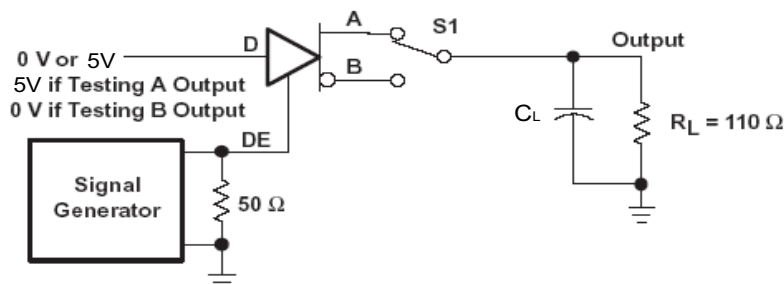


Figure 5. Driver Enable/Disable Test Circuit and Waveforms, High Output

Typical Test Circuits

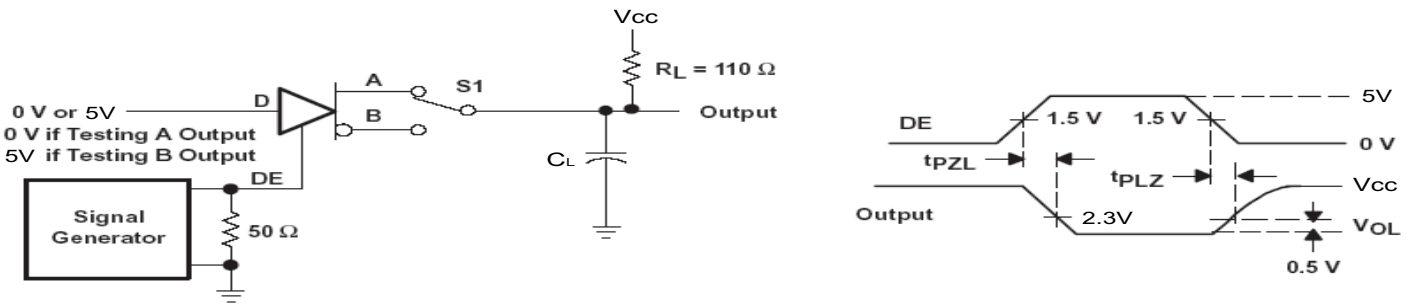


Figure 6. Driver Enable/Disable Test Circuit and Waveforms, Low Output

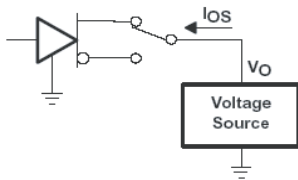


Figure 7. Driver Short-Circuit Test Configuration

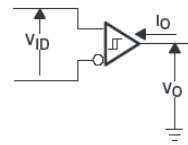


Figure 8. Receiver Parameter Definitions

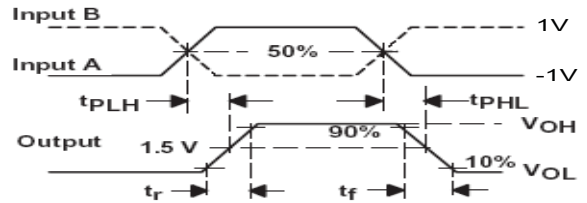
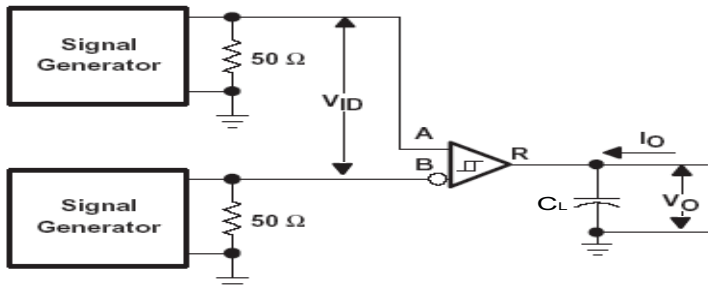


Figure 9. Receiver Propagation (t_{PLH} and t_{PHL}) Test Circuit and Waveforms

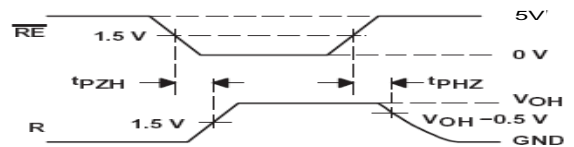
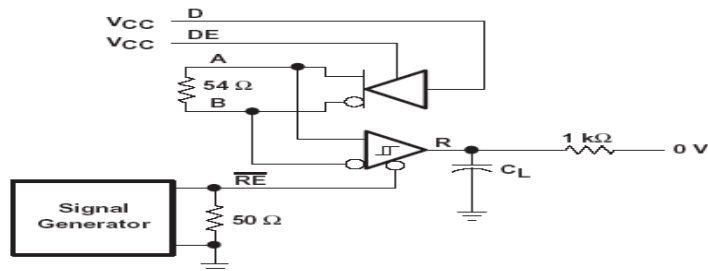


Figure 10. Receiver Output Enable/Disable Test Circuit and Waveforms, Data Output High

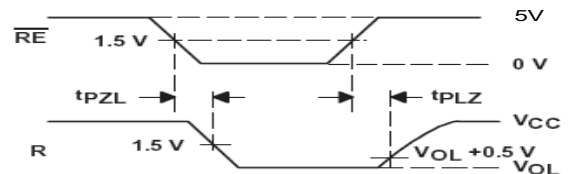
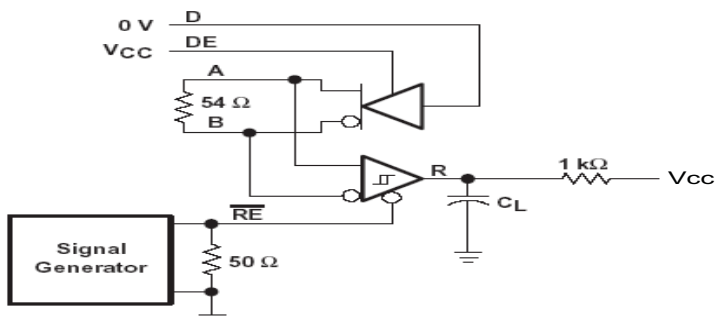
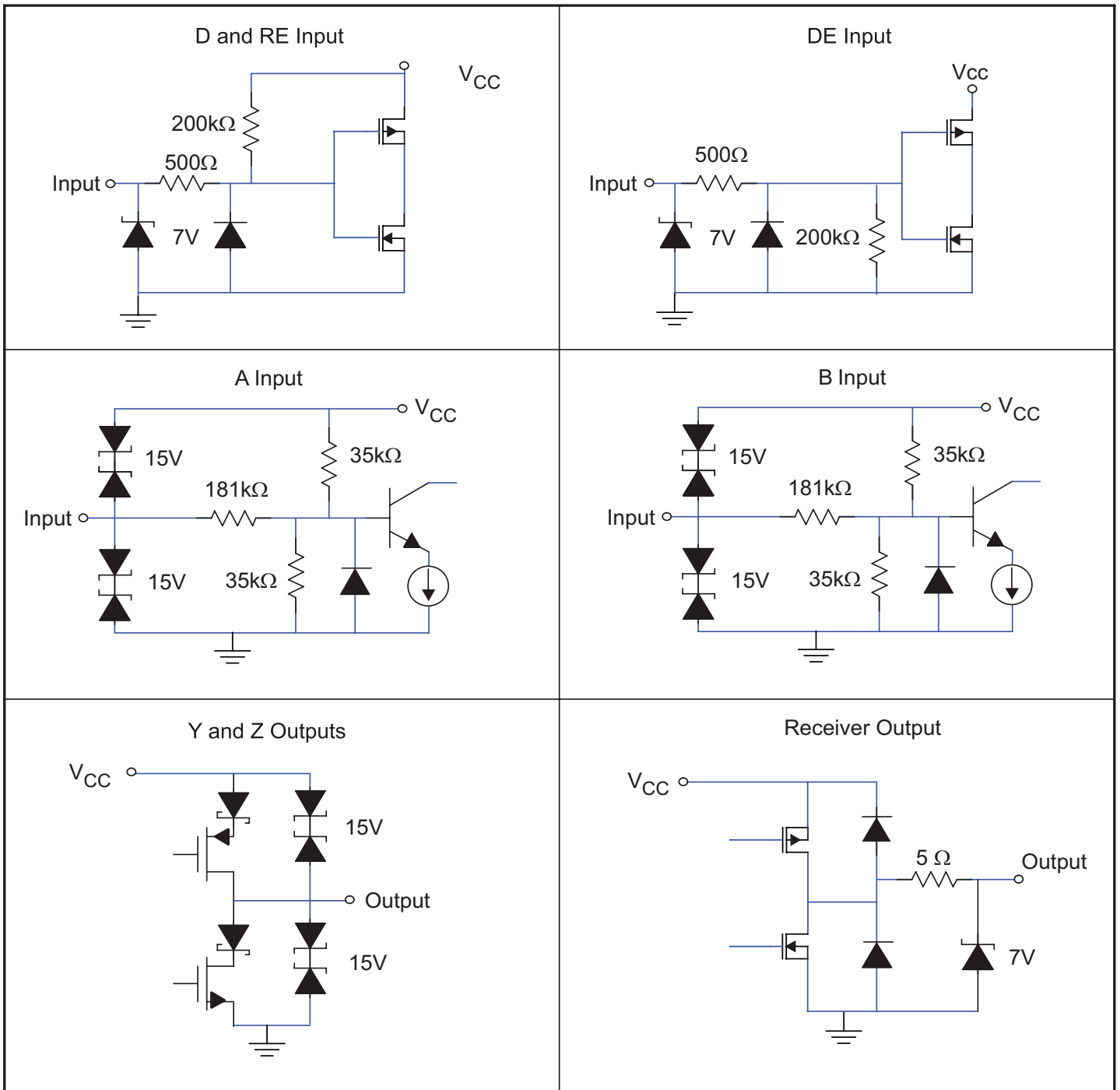
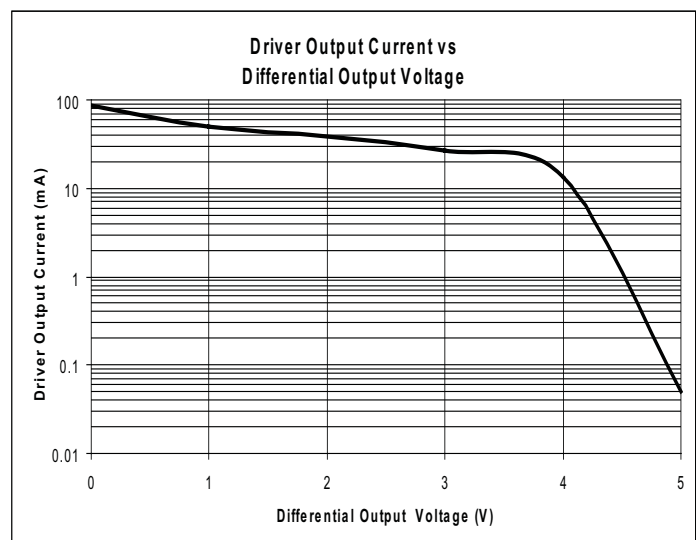
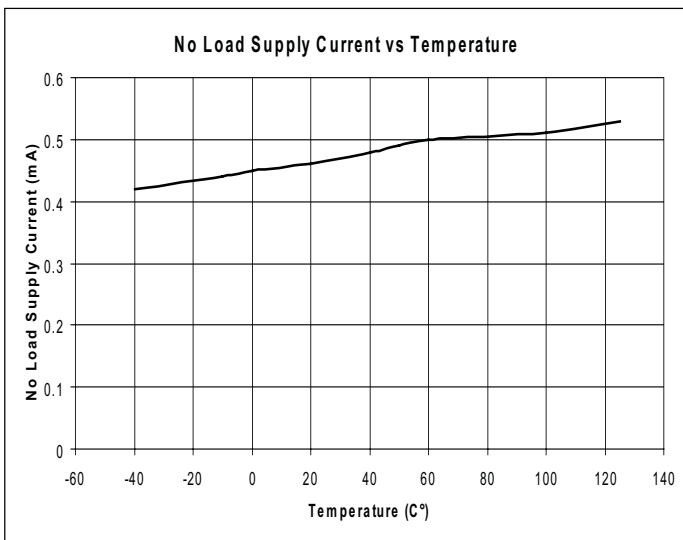
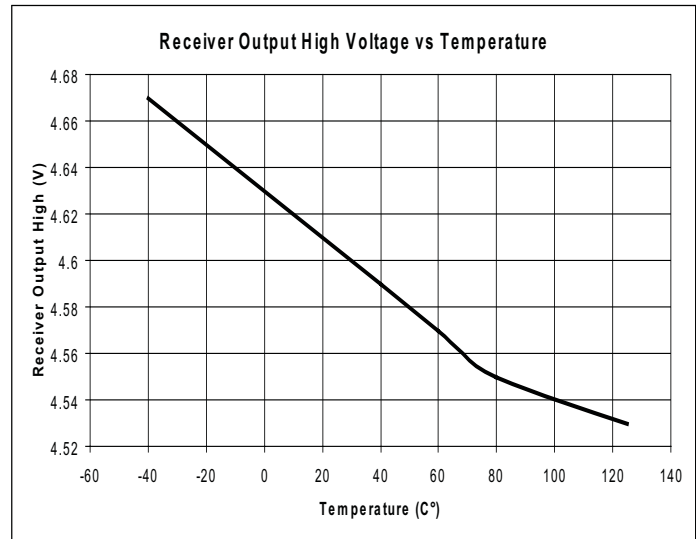
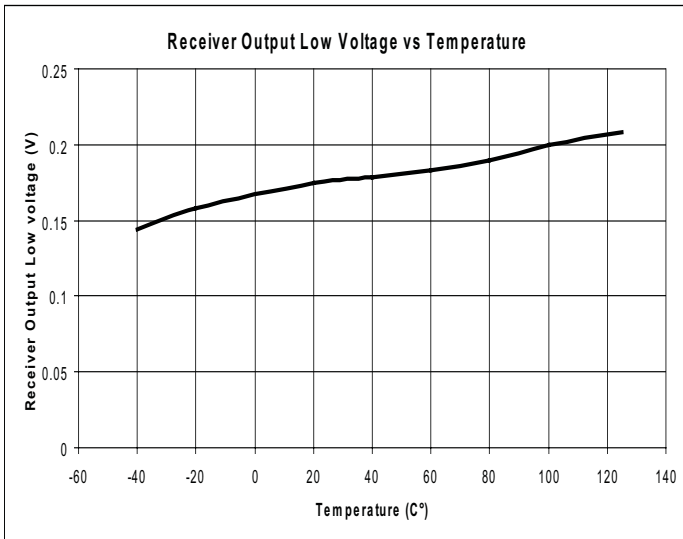
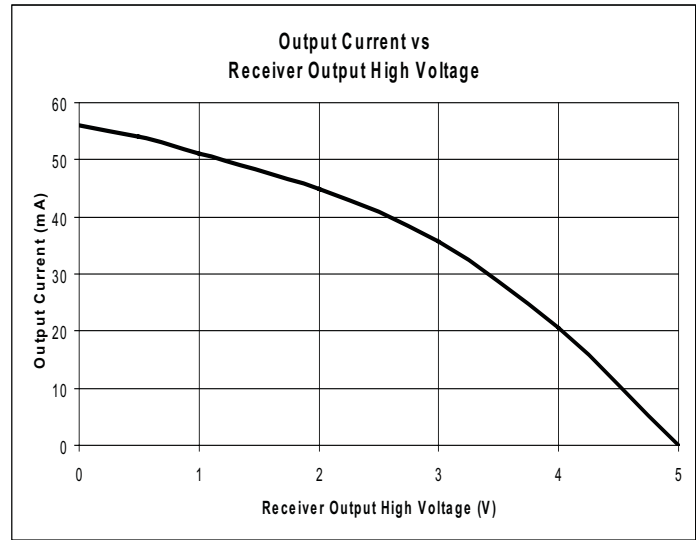
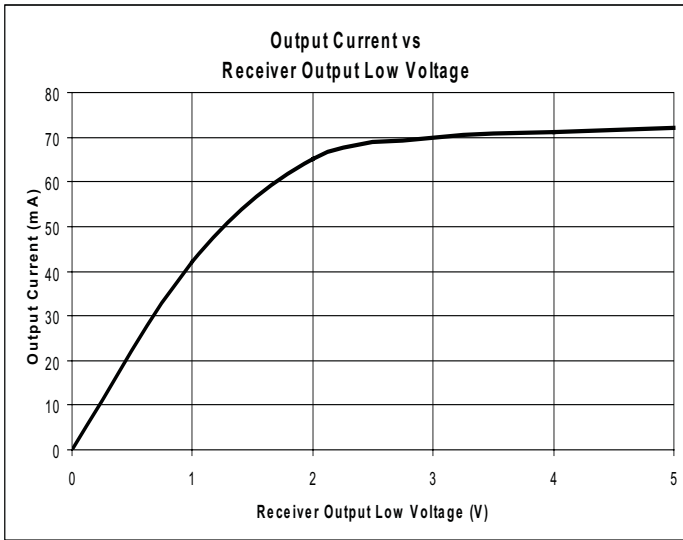


Figure 11. Receiver Output Enable/Disable Test Circuit and Waveforms, Data Output Low

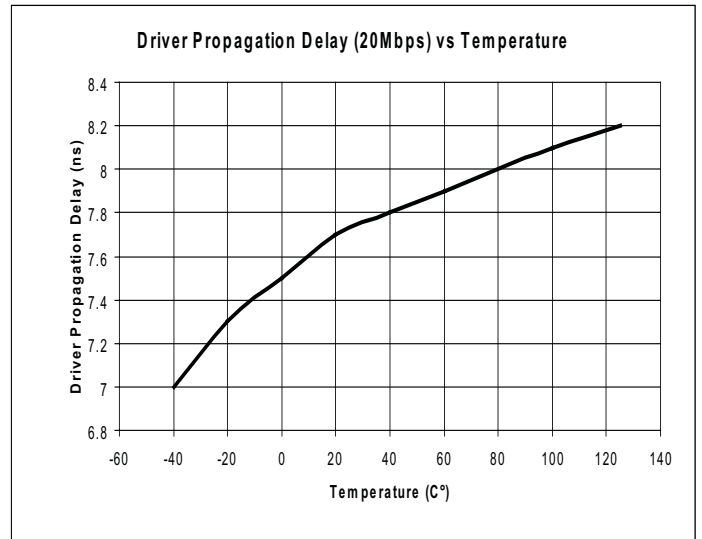
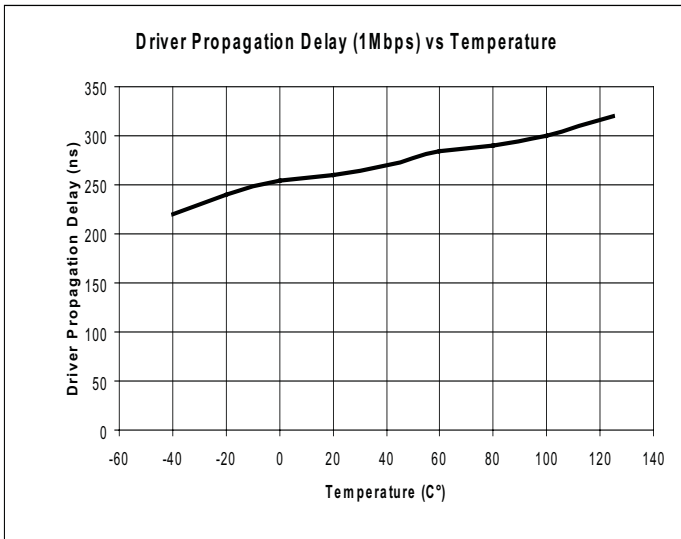
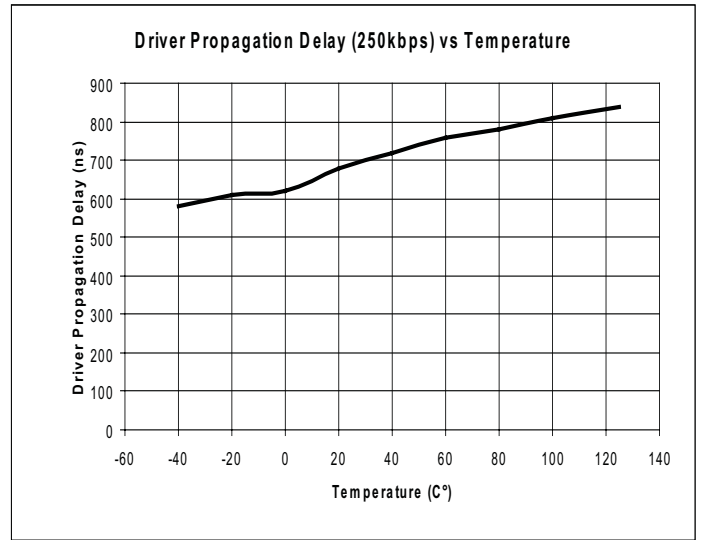
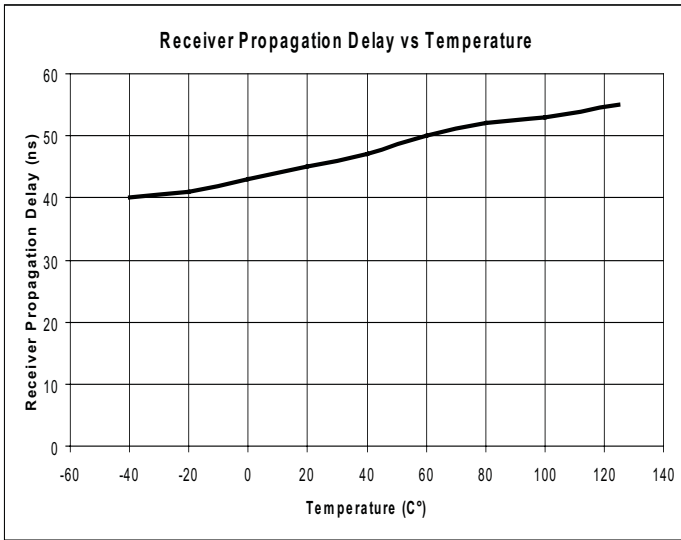
Equivalent Input and Output Schematic Diagrams



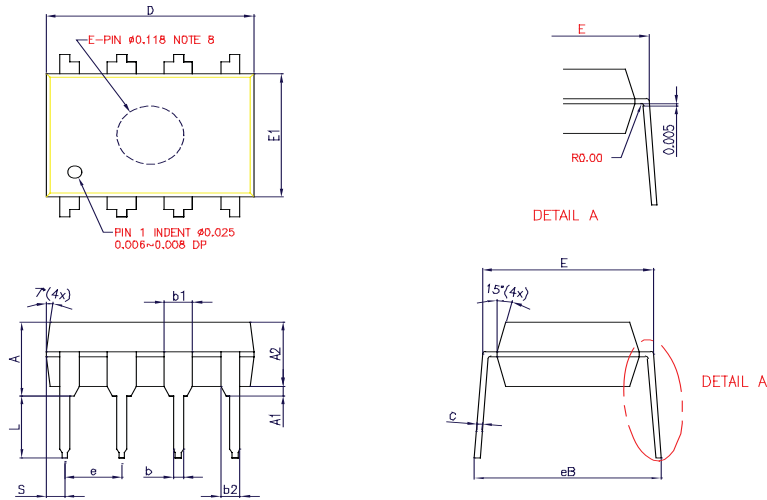
Typical Performance Characteristics



Typical Performance Characteristics



Package Information



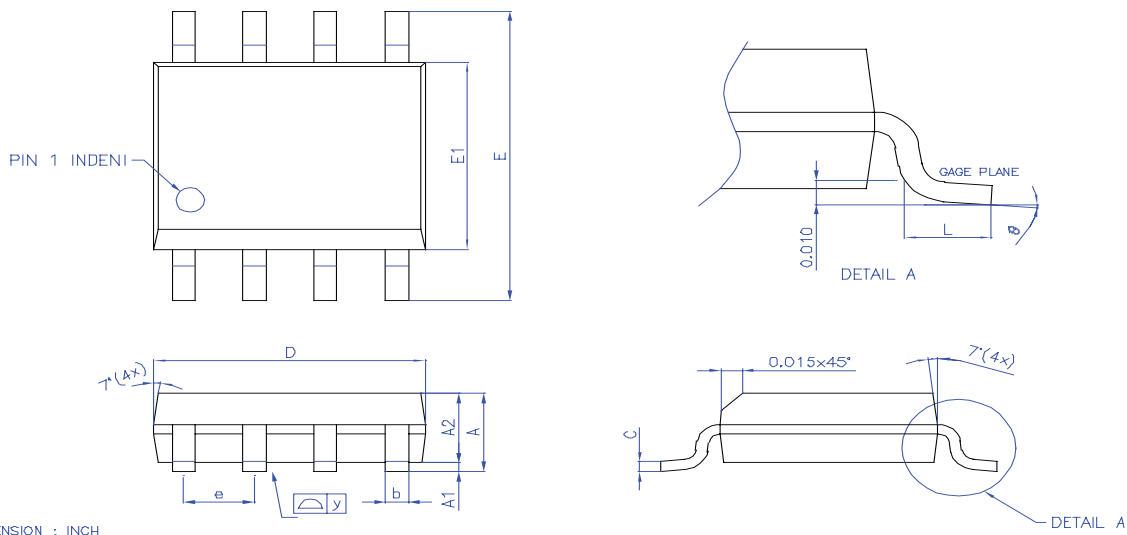
- NOTE :
1. CONTROLLING DIMENSION : INCH
 2. LEAD FRAME MATERIAL : C194
 3. DIMENSION D AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010" [0.25mm]
 4. DIMENSION "b1" DO NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSIONS SHALL NOT EXCEED 0.010" [0.25mm]. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE 0.005" [0.13mm] MINIMUM.
 5. TOLERANCE : ±0.010" [0.25mm] UNLESS OTHERWISE SPECIFIED.
 6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
 7. REFERENCE DOCUMENT : JEDEC SPEC MS-001-BA
 8. BOTTOM E-PIN INDENT ARE MARKED AS BELOW:

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	3.6	3.9	4.2	0.142	0.154	0.165
A1	0.38	—	—	0.015	—	—
A2	3.25	3.30	3.45	0.128	0.130	0.136
b	0.38	0.48	0.56	0.015	0.019	0.022
b1	1.48	1.58	1.88	0.058	0.062	0.074
b2	0.813	0.99	1.14	0.032	0.039	0.045
c	0.20	0.25	0.30	0.008	0.010	0.012
D	9.12	9.30	9.53	0.359	0.366	0.375
E	7.62	7.87	8.26	0.300	0.310	0.325
E1	6.20	6.35	6.60	0.244	0.250	0.260
e	—	2.54	—	—	0.100	—
eB	8.38	—	9.40	0.330	—	0.370
L	3.18	—	—	0.125	—	—
S	0.71	0.84	0.97	0.028	0.033	0.038

L7 TAIWAN XY X : A ~ T Y : 0 ~ 9

8-pin PDIP

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE :	
DRAW BY: Sandy Sue	01/24/00	8L P-DIP PACKAGE OUTLINE DRAWING FOR MITSUMI	
CHECK BY: Leo Chen	01/26/00	DWG. NO. PO-DIP-019	
APPROVAL: Paul Lau	01/27/00	UNIT :	SCALE : 6/1
APPROVAL: Barry Chen	1/27/00	SHEET	1 OF 1



- NOTE :
1. CONTROLLING DIMENSION : INCH
 2. LEAD FRAME MATERIAL : COPPER 194
 3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006" [0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" [0.25mm] PER SIDE.
 4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003" [0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADII OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028" [0.07mm]
 5. TOLERANCE : ±0.010" [0.25mm] UNLESS OTHERWISE SPECIFIED.
 6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
 7. REFERENCE DOCUMENT : JEDEC SPEC MS-012

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.40	0.71	1.27	0.015	0.028	0.050
y	—	—	0.076	—	—	0.003
Ø	0"	—	8"	0"	—	8"

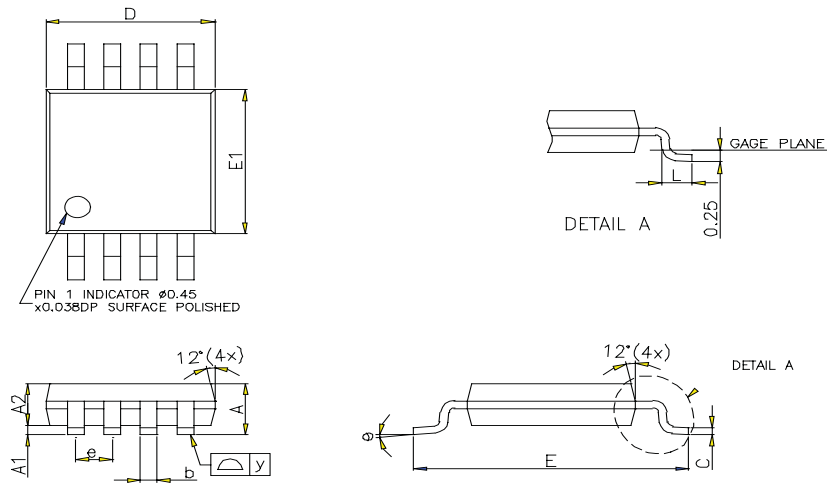
8-pin nSOIC

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE :	
DRAW BY: Dick Chen	05/21/01	8L NARROW BODY SMALL OUTLINE PACKAGE DRAWING	
CHECK BY: Yuan Liu	06/01/01	DWG. NO. PO-SOP-001	
APPROVAL: Yuan Tsai	06/01/01	UNIT :	SCALE : 15/1
APPROVAL: Yuan Tsai	06/01/01	SHEET	1 OF 1



Specifications subject to change without notice

Package Information



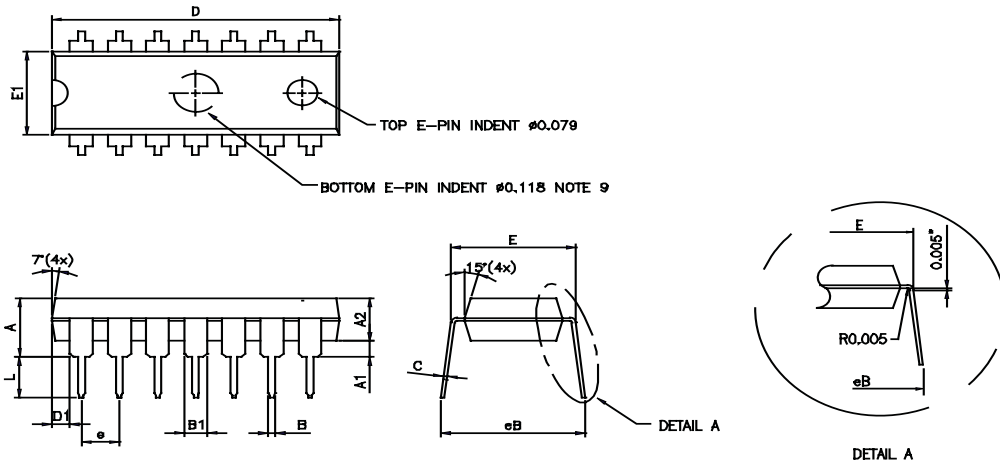
NOTE :

1. CONTROLLING DIMENSION : mm
2. LEAD FRAME MATERIAL : QLIN C7025
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006"[0.15mm] PER END. DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010"[0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003"[0.08mm] TOTAL IN EXCEED OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028"[0.07mm].
5. TOLERANCE : ±0.010"[0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLDW ACCEPTABLE SPEC.

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.81	1.02	1.10	0.032	0.040	0.043
A1	0.05	—	0.15	0.002	—	0.006
A2	0.76	0.86	0.95	0.030	0.034	0.037
b	0.28	0.30	0.38	0.011	0.012	0.015
c	0.13	0.15	0.23	0.005	0.006	0.009
d	2.90	3.00	3.10	0.114	0.118	0.122
E	4.80	4.90	5.00	0.189	0.193	0.197
E1	2.90	3.00	3.10	0.114	0.118	0.122
e	—	0.65	—	—	0.0256	—
L	0.40	0.53	0.66	0.016	0.021	0.026
y	—	—	0.076	—	—	0.003
Ø	Ø	3"	6"	0"	3"	6"

8-pin MSOP

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE :	
DRAW BY: Sandy Sue	03/01/08	8L MSOP PACKAGE OUTLINE DRAWING	
CHECK BY: Parker Chen	03/02/08		
APPROVAL: Andy Yang	03/04/08	DWG. NO. PO-MSOP-001	REV. 2
APPROVAL: CK Yeh	03-05-2008	UNIT : mm	SCALE : 1:1
		SHEET 1 OF 1	



NOTES :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : C194
3. PACKAGE DIMENSION EXCLUDE MOLDING FLASH
4. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.013" MAX
5. AFTER SOLDER DIPPING LEAD THICKNESS WILL BE 0.020" MAX
6. THE MAX. ALLOWABLE MOLDING FLASH IS 0.010"
7. TOLERANCE : 0.002" UNLESS OTHERWISE SPECIFIED
8. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPES
9. THE BOTTOM E- PIN INDENT IS MARKED AS BELOW :

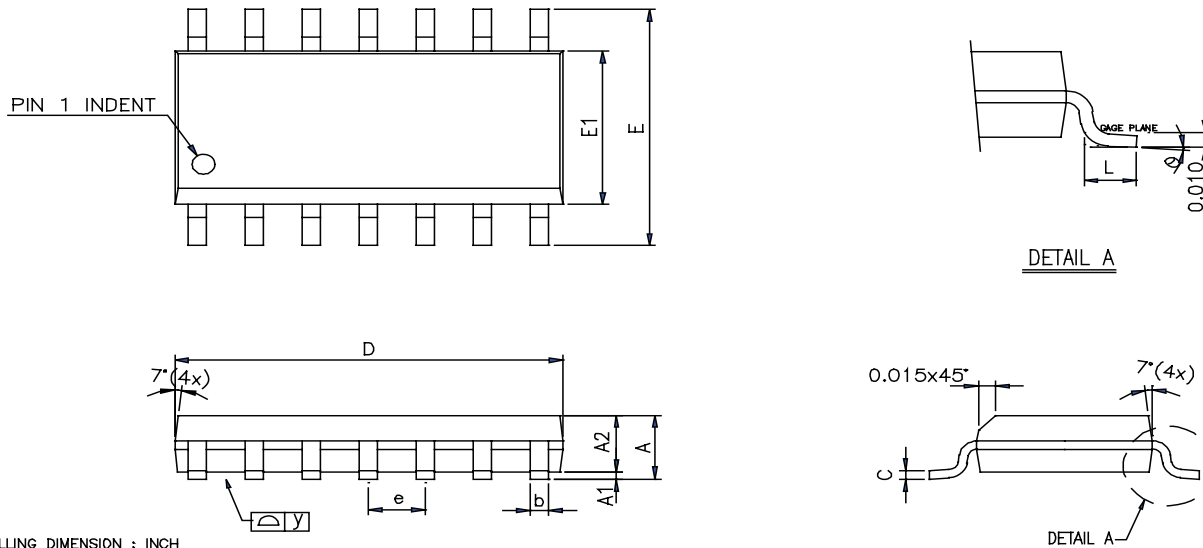


X : A-1
Y : 0-9

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	4.57	—	—	0.180
A1	0.38	—	—	0.015	—	—
A2	3.25	3.30	3.45	0.128	0.130	0.136
B	0.26	0.46	0.56	0.014	0.018	0.022
B1	1.14	1.27	1.52	0.045	0.050	0.060
C	0.20	0.25	0.33	0.008	0.010	0.013
D	18.19	18.15	19.30	0.744	0.754	0.760
D1	0.81	1.19	1.47	0.032	0.047	0.058
E	7.82	—	8.26	0.300	—	0.325
E1	6.35	6.50	6.65	0.250	0.256	0.262
e	—	2.54	—	—	0.100	—
L	3.18	—	—	0.125	—	—
eB	8.83	—	9.85	0.340	—	0.380

14-pin PDIP

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE :	
DRAW BY: <i>Hui Chen</i>	02/12/00	14L P-DIP PACKAGE	
CHECK BY: <i>Thomas Kao</i>	5/12/00	OUTLINE DRAWING	
APPROVAL: <i>Fred Kao</i>	5/12/00	DWG. NO. PO-DIP-002	REV. 0
APPROVAL: <i>Henry Chen</i>	5/12/00	UNIT : INCH	SCALE : 4/1
		SHEET 1 OF 1	



NOTE :

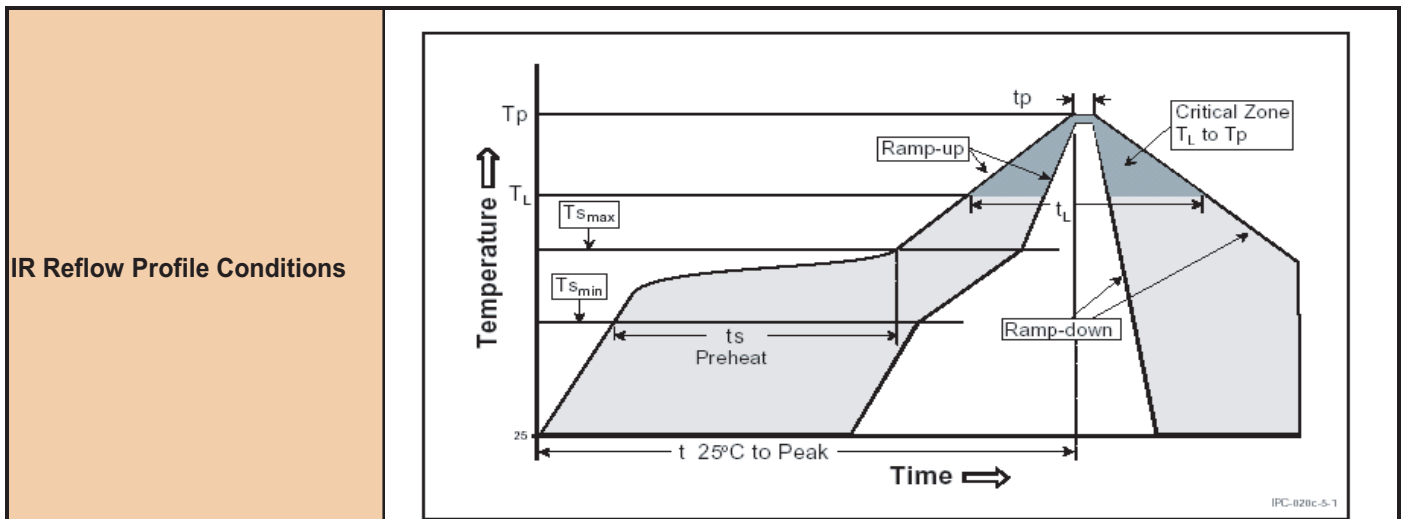
1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, THE BAR BURRS AND GATE BURRS. MOLD FLASH, THE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006" [0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" [0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003" [0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028" [0.07mm]
5. TOLERANCE : ± 0.010 [0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MS-012

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	8.53	8.64	8.74	0.336	0.340	0.344
E	5.79	5.99	6.20	0.228	0.236	0.244
E1	3.81	3.91	3.99	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.40	0.71	1.27	0.016	0.028	0.050
y	—	—	0.076	—	—	0.003
e'	0"	—	8"	0"	—	8"

14-pin nSOIC

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE :	
DRAW BY: <i>Stanley Suen</i>	01/07/00	14L NARROW BODY SMALL	
CHECK BY: <i>Yuan Sun</i>	01/07/00	OUTLINE PACKAGE DRAWING	
APPROVAL: <i>Thomas Chen</i>	01/07/00	DWG. NO. PO-SOP-002	REV. 1
APPROVAL: <i>Andy Yung</i>	01/07/00	UNIT : INCH	SCALE : 12/1
		SHEET 1 OF 1	



























Green Package SMD IR Reflow Profile Information



Profile Feature	JESD Sn-Pb Eutectic Assembly	JESD Pb-free Assembly
Average Ramp-Up Rate (T_{Smax} to T_p)	3°C/second max.	3°C/second max.
Pre-heat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (T_{Smin} to t_{Smax})	60~120 seconds	60~180 seconds
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 seconds	60~150 seconds
Peak/Classification Temperature (T_p)	235°C+5/-0°C	255°C+5/-0°C
Time within 5°C of actual Peak Temperature (t_p)	10~30 seconds	20~40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Zywyn Green Packages are Pb-free and RoHS compliance.

Ordering Information

Part Number	Temperature Range	Package Type (Green)	MOQ/Tube	MOQ/T&R
ZT3080LEEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3080LEEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3080LJEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3080LJEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3081LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3081LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3081LEEU	-40°C to +85°C	8-pin MSOP 	50	2500
ZT3082LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3082LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3082LEEU	-40°C to +85°C	8-pin MSOP 	50	2500
ZT3083LEEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3083LEEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3083LJEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3083LJEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3084LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3084LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3084LEEU	-40°C to +85°C	8-pin MSOP 	50	2500
ZT3085LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3085LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3085LEEU	-40°C to +85°C	8-pin MSOP 	50	2500
ZT3086LEEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3086LEEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3086LJEN	-40°C to +85°C	14-pin Nsoic 	100	2500
ZT3086LJEP	-40°C to +85°C	14-pin PDIP 	60	N/A
ZT3087LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3087LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3087LEEU	-40°C to +85°C	8-pin MSOP 	50	2500
ZT3088LEEN	-40°C to +85°C	8-pin Nsoic 	100	2500
ZT3088LEEP	-40°C to +85°C	8-pin PDIP 	60	N/A
ZT3088LEEU	-40°C to +85°C	8-pin MSOP 	50	2500

Please contact the factory for pricing, availability on Tape-and-Reel and Die Sales options.

Part Marking Information

TOPSIDE MARK INSTRUCTIONS:

Line 1: Zywyn (logo)
 Line 2: Zywyn Part Number "ZT3082LEEN"
 Line 3: Date Code: (Last 2 digits of Prod. Year & Prod. Work Week)
 Note: Pin # 1 "Δ" Indicator Required

BOTTOMSIDE MARK INSTRUCTIONS:

Line 1: Country of Origin (optional if Country of Origin is in Ejector Pin)
 Line 2: Lot Number

8/14-pin PDIP or 8/14-pin nSOIC

TOPSIDE MARK INSTRUCTIONS:

Line 1: Zywyn Part Name "ZT30"
 Line 2: Zywyn Part Number "88LU"
 Line 3: Date Code: (Last 2 digits of Prod. Year & Prod. Work Week)
 Note: Pin # 1 "○" Indicator Required

BOTTOMSIDE MARK INSTRUCTIONS:

Line 1: Country of Origin (optional if Country of Origin is in Ejector Pin)
 Line 2: Lot Number

8-pin MSOP

Zywyn Corporation

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